

## Introduction

This chapter provides package information for HardCopy® III devices.

## Device and Package Information

HardCopy III device and package reference information is listed in [Table 12–1](#).

**Table 12–1. HardCopy III Devices in FBGA Packages Reference**

Device	Package	Pins
HC325W	FineLine BGA - Wire Bond	484
		780
HC325F	FineLine BGA - Flip Chip	484
		780
HC335L	FineLine BGA - Flip Chip	1152
		1517
HC335F	FineLine BGA - Flip Chip	1152
		1517



For thermal resistance specifications and device package outlines for HardCopy III devices, refer to the [Altera Device Package Information Data Sheet](#).

## Document Revision History

[Table 12–2](#) shows the revision history for this document.

**Table 12–2. Document Revision History**

Date	Version	Changes
January 2011	3.1	<ul style="list-style-type: none"> <li>■ Updated <a href="#">Table 12–1</a>: removed device HC315W.</li> <li>■ Used new document template.</li> </ul>
June 2009	3.0	<ul style="list-style-type: none"> <li>■ Added non-socket replacement packaging information.</li> <li>■ Updated the new part numbers.</li> </ul>
December 2008	2.0	Made minor editorial changes.
May 2008	1.0	Initial release.

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